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**IN THE CLAIMS:**

1. (Original) A method, comprising:  
providing a substrate having a metal layer formed thereabove;  
performing a chemical mechanical polishing process on said layer of metal in the presence of a polishing slurry;  
measuring at least a concentration of a material comprising said metal layer in said polishing slurry used during said polishing process after at least some of said polishing process has been performed; and  
determining a thickness of said layer of metal removed during said polishing process based upon at least said measured concentration of said material comprising said metal layer.
2. (Original) The method of claim 1, further comprising adjusting at least one parameter of said polishing process based upon said determined thickness of said layer of metal removed during said polishing process.
3. (Original) The method of claim 1, further comprising measuring a volume of said polishing slurry used during said polishing process.
4. (Original) The method of claim 3, further comprising calculating a thickness of said layer of metal removed during said polishing process based upon at least the measured volume of said polishing slurry used during said polishing operation.